



250V P-CHANNEL ENHANCEMENT MODE MOSFET

Features and Benefits

Complementary N-channel Type ZVN4525E6

UL Flammability Classification Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020

Solderable per MIL-STD-202, Method 208 @3

Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)

Halogen and Antimony Free. "Green" Device (Note 3)

Qualified to AEC-Q101 Standards for High Reliability

High voltage Low on-resistance Fast switching speed Low gate drive Low threshold

SOT23-6 package

Mechanical Data

Case Material: Molded Plastic.

Weight 0.018 grams (Approximate)

Case: SOT26

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25℃
-250V	14Ω @ V _{GS} = -10V	-197mA
-250 V	18Ω @ V _{GS} = -3.5V	-175mA

Description

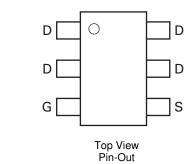
This 250V enhancement mode P-channel MOSFET provides users with a competitive specification. It offers efficient power handling capability, high impedance and is free from thermal runaway and thermally induced secondary breakdown. Applications benefiting from this device include a variety of Telecom and general high voltage circuits.

SOT89 and SOT223 versions are also available.

Applications

- Earth Recall and Dialing Switches
- Electronic Hook Switches
- High Voltage Power MOSFET Drivers
- Telecom Call Routers
- Solid State Relays





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Terminals: Finish - Matte Tin Annealed over Copper Leadframe.

Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Quantity per reel
ZVP4525E6TA	SOT26	3,000
ZVP4525E6TC	SOT26	3,000

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

 See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

				SOT26 P52	λM	YM = Dat Y Y or $\overline{Y} = \overline{Y}$	oduct Type te Code Ma Year (ex: C Month (ex	arking C = 2015)				
Date Code Key												
Year	2015		2016	2017		2018	2019		2020	2021		2022
<u> </u>												
Code	C		D	E		F	G		Н			J
		Eab			May	,		Aug	-	 Oct	Nov	-
Code Month Code	C Jan	Feb 2	D Mar 3	E Apr	May 5	F Jun 6	G Jul	Aug	Н Sep 9	Oct	Nov N	J Dec

ZVP4525E6 Document Number DS33411 Rev. 2 - 2



Maximum Ratings (@T_A = +25 °C, unless otherwise specified.)

(Characteristic		Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-250	V
Gate-Source Voltage			V _{GS}	±40	V
Continuous Drain Current	101	(Note 5)	۱ _D	-197	
	$V_{GS} = 10V$	T _A = +70 °C (Note 5)		-157	- mA
Pulsed Drain Current	$V_{GS} = 10V$	(Note 7)	I _{DM}	-1	A
Continuous Source Current (Body Diode)			Is	-0.75	A
Pulsed Source Current (Body Diode)			Ism	-1	Α

Thermal Characteristics (@TA = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Power Dissipation Linear Derating Factor	(Note 5)	P _D	1.1 8.8	W mW/℃
Thermal Resistance, Junction to Ambient	(Note 5)	- R _{eja}	113	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	68 -55 to +150	°C

Notes: 5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

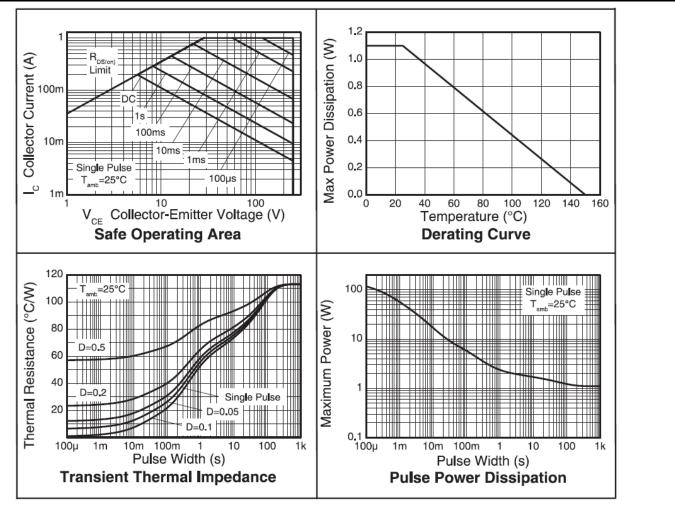
6. For a device surface mounted on FR4 PCB measured at t \leq 5 secs.

7. Repetitive rating - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.

NB High Voltage Applications

For high voltage applications, the appropriate industry sector guidelines should be considered with regard to voltage spacing between conductors.

Thermal Characteristics





Electrical Characteristics (@T_A = +25 °C, unless otherwise specified.)

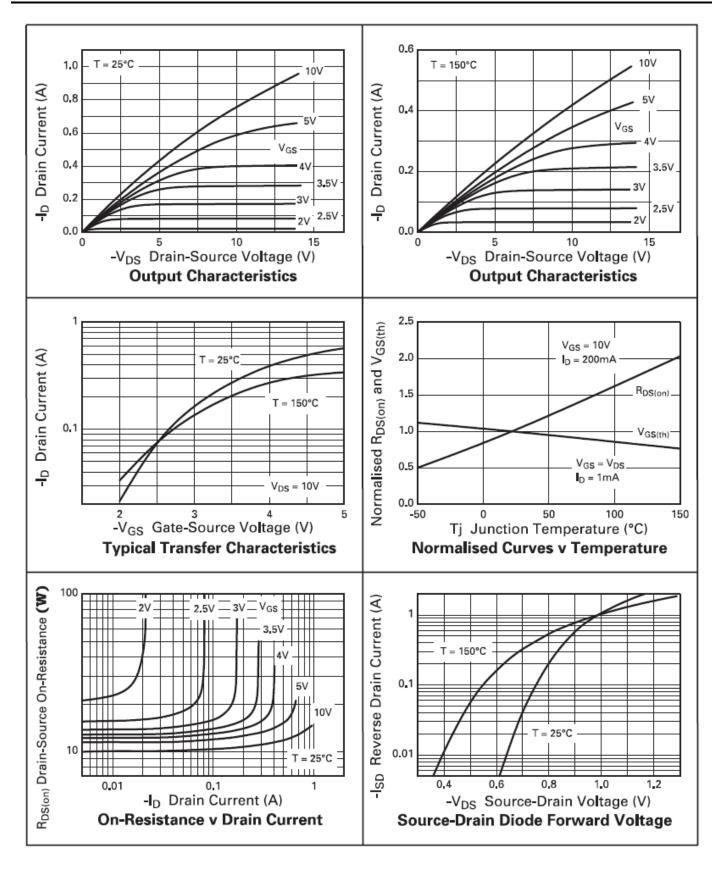
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS			, ,,			
Drain-Source Breakdown Voltage	BV _{DSS}	-250	-285	_	V	$I_{D} = -1mA, V_{GS} = 0V$
Zero Gate Voltage Drain Current	I _{DSS}	_	-30	-500	nA	V _{DS} = -250V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}		±1	±100	nA	$V_{GS} = \pm 40V, V_{DS} = 0V$
ON CHARACTERISTICS			•	•	•	
Gate Threshold Voltage	V _{GS(th)}	-0.8	-1.5	-2.0	V	$I_D = -1mA$, $V_{DS} = V_{GS}$
Statia Duain Source On Desistance (Note 9)	D		10	14	Ω	V _{GS} = -10V, I _D = -200mA
Static Drain-Source On-Resistance (Note 8)	R _{DS(ON)}		13	18		$V_{GS} = -3.5V, I_D = -100mA$
Forward Transconductance (Notes 10)	g fs	80	200	—	mS	$V_{DS} = -10V, I_D = -0.15A$
Diode Forward Voltage (Note 9)	V _{SD}		-0.86	-0.97	v	$I_{S} = -200 \text{mA}, V_{GS} = 0 \text{V},$ $T_{J} = +25 ^{\circ}\text{C}$
DYNAMIC CHARACTERISTICS (Note 10)			•	•	•	
Input Capacitance	Ciss		73	_		
Output Capacitance	Coss		12.8	_	pF	$V_{DS} = -25V, V_{GS} = 0V$ f = 1MHz
Reverse Transfer Capacitance	Crss		3.91	—		
Total Gate Charge (Note 9)	Qg		2.45	2.45		$V_{DS} = -25V, V_{GS} = -10V,$
Gate-Source Charge (Note 9)	Q _{gs}		0.22	0.31	nC	$I_D = -200 \text{mA}$ (refer to
Gate-Drain Charge (Note 9)	Q _{gd}	_	0.45	0.63		test circuit)
Turn-On Delay Time (Note 9)	t _{D(on)}		1.53	_		
Turn-On Rise Time (Note 9)	tr		3.78	_		$V_{DD} = -30V, V_{GS} = -10V$
Turn-Off Delay Time (Note 9)	t _{D(off)}		17.5	_	ns	$I_D = -200 \text{mA}, R_G = 50 \Omega$ (refer to test circuit)
Turn-Off Fall Time (Note 9)	t _f	_	7.85	_	1	
Reverse Recovery Time	t _{rr}	_	205	290	ns	I _F = -200mA, di/dt = 100A/μs,
Reverse Recovery Charge	Q _{rr}		21	29	nC	T _J = +25℃

Notes:

8. Measured under pulsed conditions. Width ≤ 300µs. Duty cycle ≤ 2%.
9. Switching characteristics are independent of operating junction temperatures.
10. For design aid only, not subject to production testing.

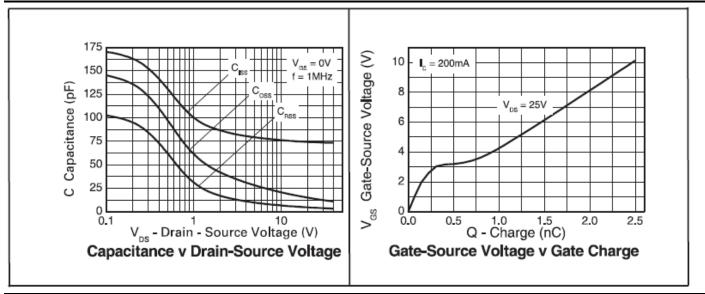


Typical Characteristics

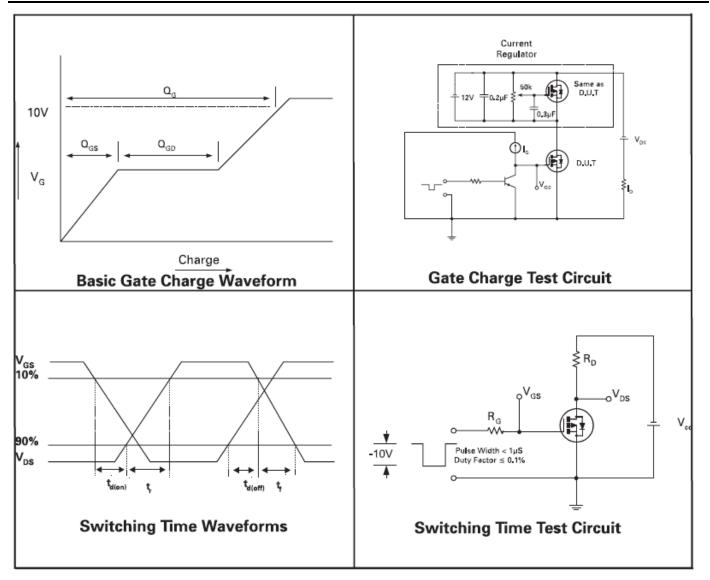




Typical Characteristics (continued)



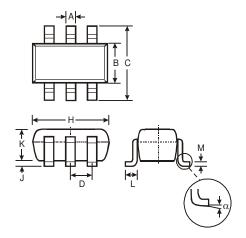
Test Circuits





Package Outline Dimensions

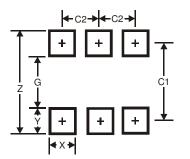
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



	SOT26						
Dim	Min	Max	Тур				
Α	0.35	0.50	0.38				
В	1.50	1.70	1.60				
С	2.70	3.00	2.80				
D		— — 0.95					
н	2.90	3.10	3.00				
J	0.013	0.10	0.05				
Κ	1.00 1.30 1.10						
L	0.35	0.55	0.40				
М	0.10	0.20	0.15				
α	0°	8°					
All D	imensi	ons in	mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.20
G	1.60
Х	0.55
Y	0.80
C1	2.40
C2	0.95



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